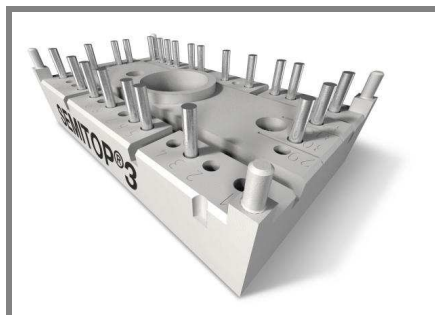


SK 10 DGDL 126 ET



SEMITOP® 3

**3-phase bridge rectifier +
brake chopper +3-phase
bridge inverter**
SK 10 DGDL 126 ET

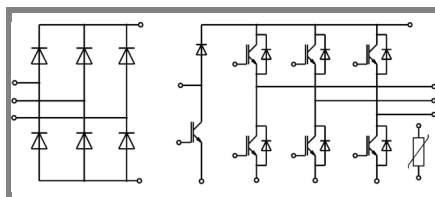
Preliminary Data

Features

- Compact design
- One screw mounting
- Heat transfer and isolation through direct copper bonded aluminum oxide ceramic (DCB)
- Trench technology IGBT
- CAL High Density FWD
- Integrated NTC temperature sensor

Typical Applications*

- Inverter



DGDL - ET

Absolute Maximum Ratings		$T_s = 25^\circ\text{C}$, unless otherwise specified	
Symbol	Conditions	Values	Units
IGBT - Inverter, Chopper			
V_{CES}	$T_s = 25 (80)^\circ\text{C}$	1200	V
I_C	$T_s = 25 (80)^\circ\text{C}$	15 (11)	A
I_{CRM}	$I_{CRM} = 2 \times I_{Cnom}$, $t_p = 1 \text{ ms}$	16	A
V_{GES}		± 20	V
T_j		-40 ... +150	$^\circ\text{C}$
Diode - Inverter, Chopper			
I_F	$T_s = 25 (80)^\circ\text{C}$	25 (17)	A
I_{FRM}	$I_{FRM} = 2 \times I_{Fnom}$, $t_p = 1 \text{ ms}$	50	A
T_j		-40 ... +150	$^\circ\text{C}$
Rectifier			
V_{RRM}	$T_s = 80^\circ\text{C}$	1600	V
I_F	$T_s = 80^\circ\text{C}$	21	A
I_{FSM} / I_{TSM}	$t_p = 10 \text{ ms}$, $\sin 180^\circ$, $T_j = 25^\circ\text{C}$	220	A
I_t^2	$t_p = 10 \text{ ms}$, $\sin 180^\circ$, $T_j = 25^\circ\text{C}$	240	A^2s
T_j		-40 ... +150	$^\circ\text{C}$
T_{sol}	Terminals, 10s	260	$^\circ\text{C}$
T_{stg}		-40 ... +125	$^\circ\text{C}$
V_{isol}	AC, 1 min. / 1s	2500 / 3000	V

Characteristics		$T_s = 25^\circ\text{C}$, unless otherwise specified			
Symbol	Conditions	min.	typ.	max.	Units
IGBT - Inverter, Chopper					
V_{CEsat}	$I_C = 8 \text{ A}$, $T_j = 25 (125)^\circ\text{C}$		1,7 (2)	2,1 (2,4)	V
$V_{GE(th)}$	$V_{GE} = V_{CE}$, $I_C = 0,3 \text{ mA}$	5	5,8	6,5	V
$V_{CE(TO)}$	$T_j = 25^\circ\text{C} (125)^\circ\text{C}$		1 (0,9)	1,2 (1,1)	V
r_T	$T_j = 25^\circ\text{C} (125)^\circ\text{C}$		87 (138)	113 (162)	m Ω
C_{ies}	$V_{CE} = 25 \text{ V}$, $V_{GE} = 0 \text{ V}$, $f = 1 \text{ MHz}$		0,7		nF
C_{oes}	$V_{CE} = 25 \text{ V}$, $V_{GE} = 0 \text{ V}$, $f = 1 \text{ MHz}$		0,2		nF
C_{res}	$V_{CE} = 25 \text{ V}$, $V_{GE} = 0 \text{ V}$, $f = 1 \text{ MHz}$		0,1		nF
$R_{th(j-s)}$	per IGBT			2	K/W
$t_{d(on)}$	under following conditions		85		ns
t_r	$V_{CC} = 600 \text{ V}$, $V_{GE} = \pm 15 \text{ V}$		30		ns
$t_{d(off)}$	$I_C = 8 \text{ A}$, $T_j = 125^\circ\text{C}$		430		ns
t_f	$R_{Gon} = R_{Goff} = 75 \Omega$		90		ns
E_{on}	inductive load		1		mJ
E_{off}			1		mJ
Diode - Inverter, Chopper					
$V_F = V_{EC}$	$I_F = 8 \text{ A}$, $T_j = 25 (125)^\circ\text{C}$		1,9 (2)	2,2	V
$V_{(TO)}$	$T_j = 25^\circ\text{C} (125)^\circ\text{C}$		1 (0,8)	1,1 (0,9)	V
r_T	$T_j = 25^\circ\text{C} (125)^\circ\text{C}$		40 (53)	47	m Ω
$R_{th(j-s)}$	per diode			2,1	K/W
I_{RRM}	under following conditions		21		A
Q_{rr}	$I_F = 15 \text{ A}$, $V_R = 600 \text{ V}$		3,5		μC
E_{rr}	$V_{GE} = 0 \text{ V}$, $T_j = 125^\circ\text{C}$		1,4		mJ
	$di_F/dt = 570 \text{ A}/\mu\text{s}$				
Diode rectifier					
V_F	$I_F = 15 \text{ A}$, $T_j = 25 (125)^\circ\text{C}$		1,1		V
$V_{(TO)}$	$T_j = 150^\circ\text{C}$		0,8		V
r_T	$T_j = 150^\circ\text{C}$		20		m Ω
$R_{th(j-s)}$	per diode			2,7	K/W
Temperatur sensor					
R_{ts}	5 %, $T_r = 25 (100)^\circ\text{C}$		5000(493)		Ω
Mechanical data					
w			30		g
M_s	Mounting torque			2,5	Nm

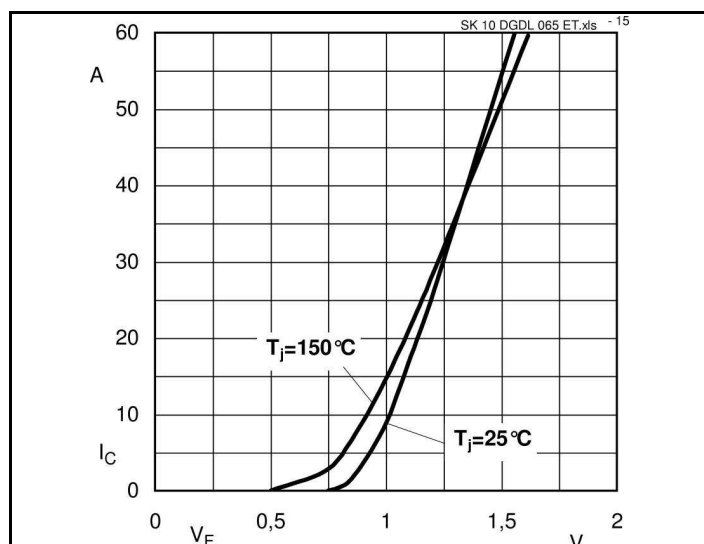


Fig. 15 Input Bridge Diode forward characteristic

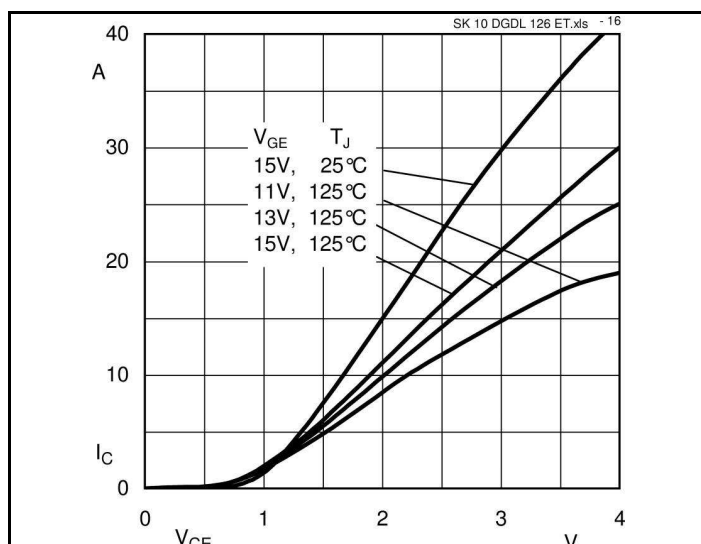


Fig. 16 Typical Output Characteristic

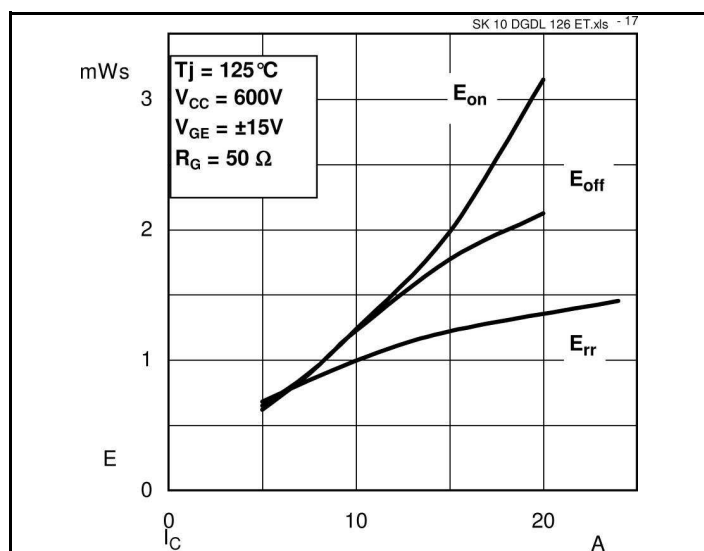


Fig. 17 Turn-on/off energy = $f(I_C)$

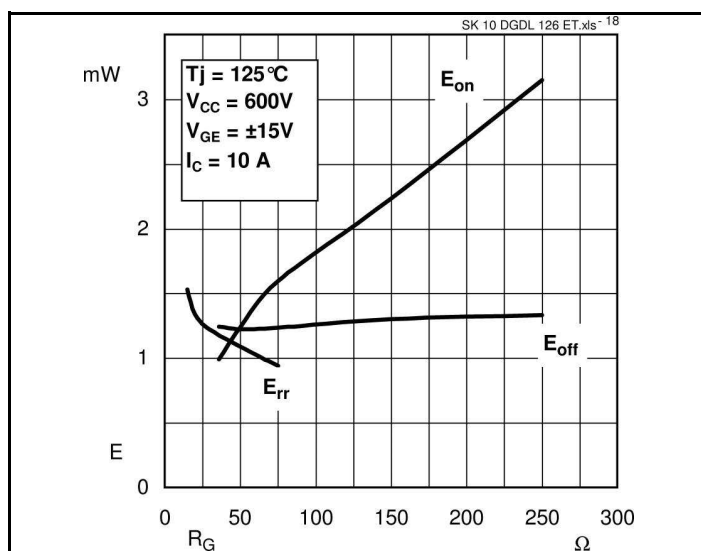


Fig. 18 Turn-on/off energy = $f(R_G)$

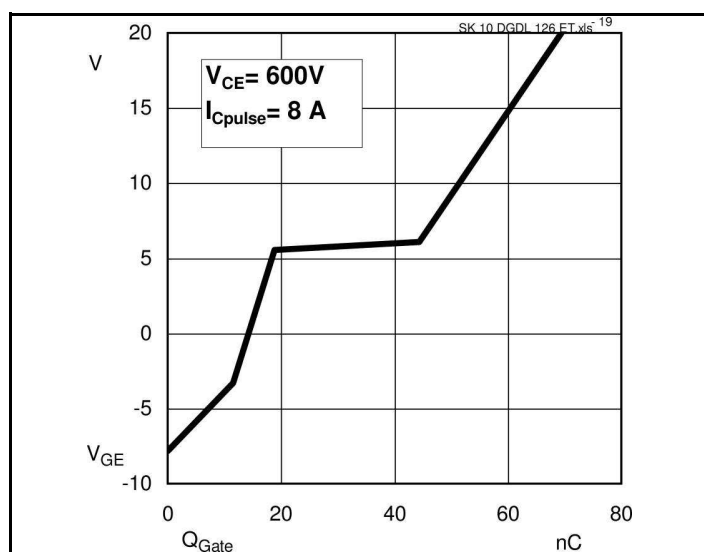


Fig. 19 Typical gate charge characteristic

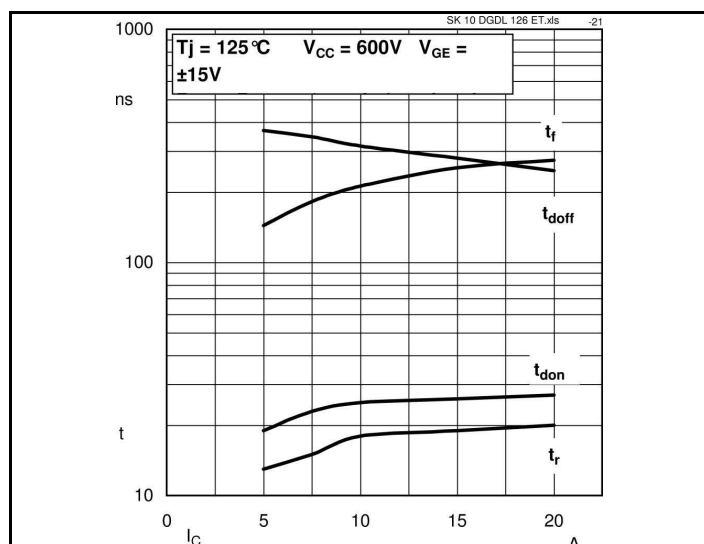


Fig. 21 Typical switching time vs. I_C

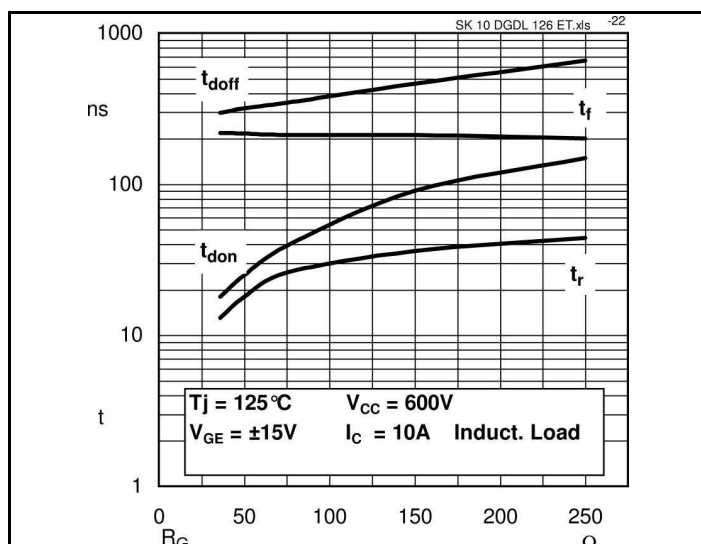


Fig. 22 Typical switching time vs. R_G

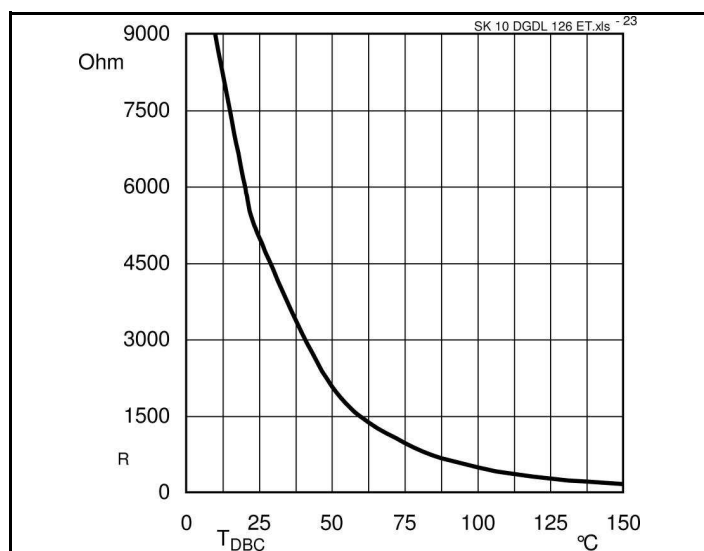


Fig. 23 Typical NTC characteristic

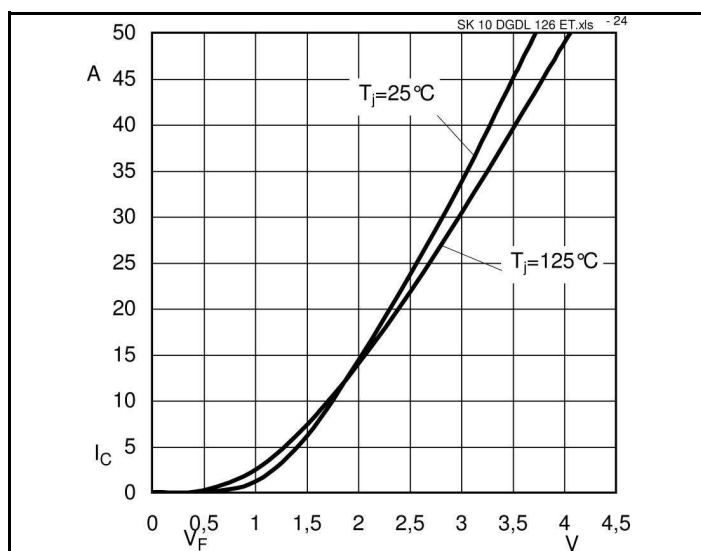
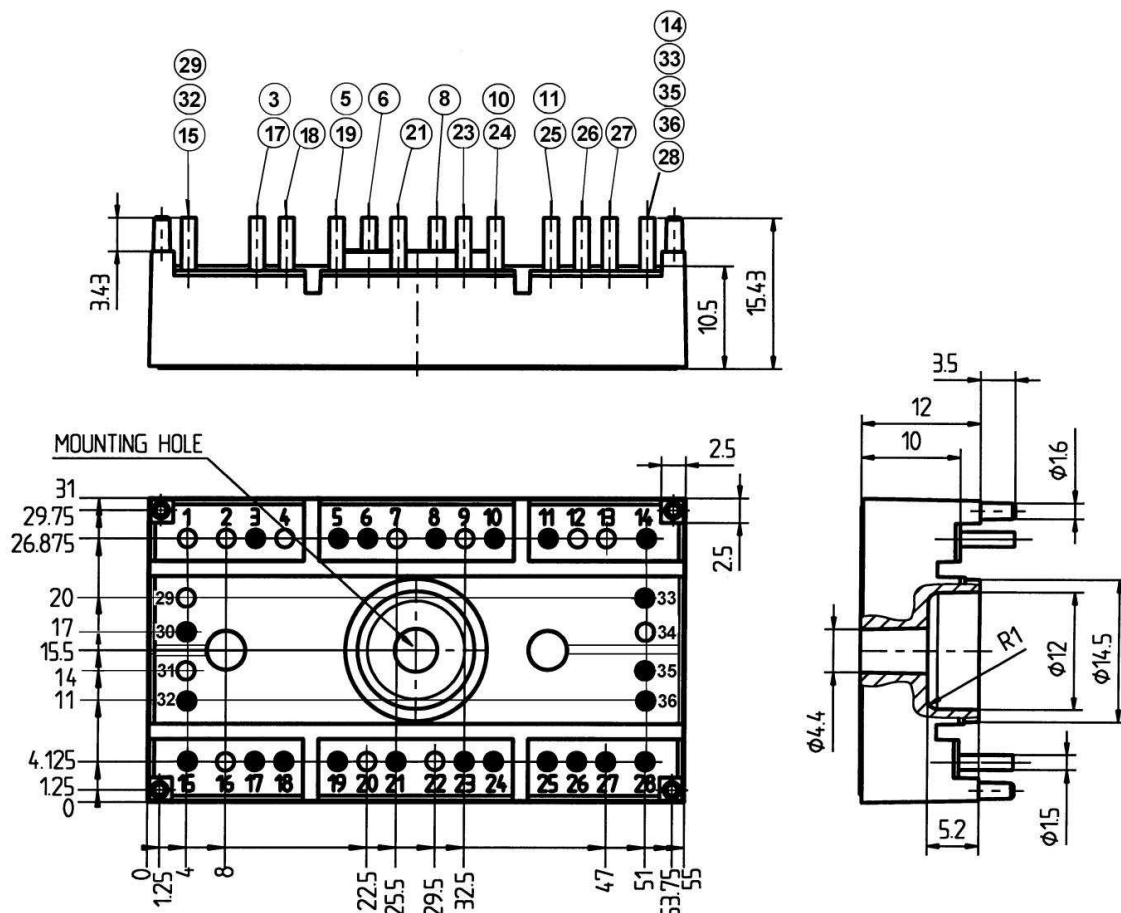


Fig. 24 Typical FWD forward characteristic

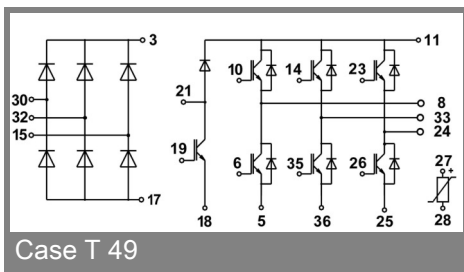
SK 10 DGDL 126 ET

UL Recognized
File no. E63 532

Dimensions in mm



Case T 49 (Suggested hole diameter, in the PCB, for solder pins and plastic mounting pins: 2mm)



Case T 49

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our personal.